

Multi-Mode Dual-Side Probing

4060 ==

6X MULTI-FUNCTION FLYING PROBE TESTER

IDEAL FOR VOLUME PRODUCTION, BACKPLANES, LOAD BOARDS, PROBE CARDS ... 8 MORE



4060 S2

Probing without limits

Multi-Mode Dual-Side Probing

4060 S2 combines the advantages of dual-side flying probing, with the possibility to use additional tools such as fixed probes, planarity supports, mini bed-of-nails fixtures, and more.

DUAL-SIDE FLYING PROBING. Four top-side and two bottom-side moving heads make 4060 S2 able to perform flying probe test on both sides of the board simultaneously, increasing **throughput** and **test capabilities.**

- Reduced test time
- Increased test coverage
- Single test program for the 2 sides of the board

Each flying probe can be used for in-circuit test, power-on test, sink/source analog, digital D/S, flashing via on-board programming, boundary scan, prescaler.

BOTTOM MULTI-PROBE FLYING HEADS. In addition to electrical probes for electrical tests, the two **bottom multi-probe flying heads** can move high-speed power probes, support rods, hi-res cameras, multi-probes, laser & LED probes and electro scan probes, covering the most comprehensive test needs.

MULTI-MODE PROBING. While using the 4 top-side probes to perform flying probe test, 2 bottom moving platforms can be used for bed-of-nails fixtures, multiple high-current power supplies, digital I/O, high-speed signals. The **dynamic planarity supports** allow you to **reliably test large and thin boards**, avoiding PCB vibrations due to probe strokes.

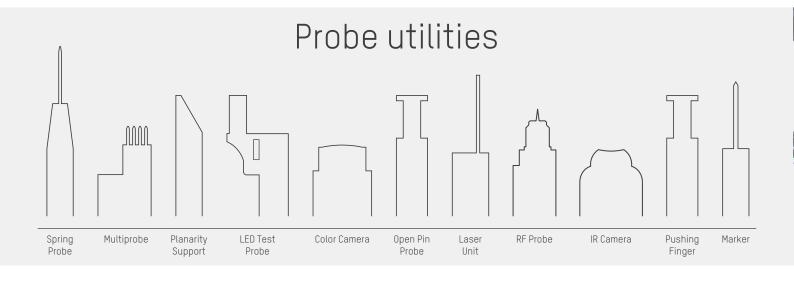


Test even the biggest ones.

IDEAL FOR LARGE AND HEAVY BOARDS. The large test area allows 4060 S2 to fit boards with up to $1000 \times 610 \text{mm}$ [39.4 x 24"] size, while the input conveyor module makes it easy to load the heaviest boards (e.g. load boards, power modules, telecom boards), up to 20 Kg weight, which are automatically loaded into the test area.

TALL COMPONENTS. 4060 S2 tests also PCBs with transformers, heat sinks, connectors, front panels, polarized capacitors and other tall components up to 110mm. No-fly zones and contacting quotes are automatically defined, while the system is able to contact points at different heights simultaneously.

BACKPLANES. 4060 S2 can test backplanes mounting any type of connector. The system can execute, simultaneously on both sides of the board, complete test of continuity, insulation, presence and orientation of connectors and components, correct assembly and mechanical check of the contact pins.





In-Circuit Test 100% Short Circuit Test



Nodal Impedance



Open Pin Scan



Power-On Test



Functional Test



Optical Test

Fast and accurate probing. On the smallest components.

ULTRA HIGH-SPEED AXES. Full linear motion on XYZ axes brings the probes to unprecedented speed. No other motion technologies, such as rotary and planar motors, can reach this productivity level.

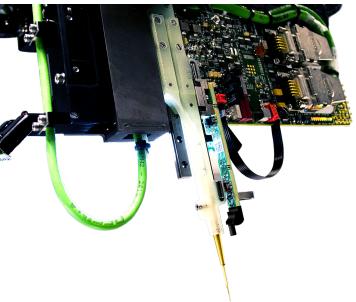
ACCURATE MICRO-PAD CONTACTING. Motion accuracy of linear motors is perfectioned by linear optical encoders, mounted on each axis and thus able to provide real feedback of probe positioning with sub-micron resolution. Benefiting from this technology, 4060 S2 is able to reliably probe micro-SMT components, as well as directly probe card contactors, or male/female contactor pins (e.g. on backplanes).

ULTRA-FAST SOFT TOUCH TECHNOLOGY. With the Sinusoidal Motion **Profile**, the probe lands on the board with near-zero energy. This allows high-productivity testing of sticky boards and flex circuits, or micro SMDs such as 01005 and 008004, leaving no visible mark on the test point.

Measurement Accuracy

The shorter the distance between probe and instruments, the faster and more accurate is the measurement. According to this simple rule, SPEA designed the concept of Flying Tester Technology. Force & measurement instruments are placed directly on each flying head, delivering unsurpassed measurement speed and performance.

- Highest measurement performance & accuracy (0.1pF)
- Signal integrity
- No measurement degradation or interference
- Immediate signal acquisition (within hundreds microseconds)







LED Light Test





Boundary Scan



Thermal Test



Waveform Capture







5G RF Test



Leonardo 0S2.

Easy. Fast. Self-programming

- Automatic test program generation in **minutes**
- Automatic test program generation with or without CAD file
- 50% test program generation time with S2 System Control
- Faster & fully automatic Debug & Tuning
- Automatic board repair software
- Automatic Pick & Place X-Y file import
- Built-In Self-Test (BIST) compliant
- User-friendly intuitive graphical interface
- Control software to monitor, analyze & optimize the production process



Models







4060 S2 IL Automatic In-Line Loading



4060 S2 SL Shuttle Loader





4060 S2 BP Backplane

4060 S2 TC Operatorless Test Cell

Main Specs

Min. Package Size 008004 (0.25x0.125mm)

Multi-Probe Flying Heads 6 (4 top + 2 bottom)

Tester interface Up to 576 channels

XYZ Motion technology Linear

Linear

XYZ Measuring encoders 10µm accuracy 0.0012µm resolution

On-axis measurement instrumentation Included on each axis

Footprint (LxW) 1750 x 1272mm (2.2m²)

5.7 x 4.2ft (23.9ft²)

BOARD LOADING

Integration in SMD line or test cell with loader/unloader

Conveyor loading Left-to-Right or Right-to-Left

Left-to-Right or Right-to-Left
Pass-Through or Pass-Back

Manual loading Front and side loading

TEST AREA SPECS

Easy to use

Automatic board repair

Automatic variant management

Operating System: Leonardo OS2

Production monitor & analysis

SOFTWARE

 $\begin{array}{ccc} \mbox{Manual: } 686 \times 610 \mbox{mm } (27 \times 24'') \\ \mbox{Manual: } 686 \times 610 \mbox{mm } (27 \times 24'') \\ \mbox{In-Line: } 1000 \times 610 \mbox{mm } (39.4 \times 24'')^* \end{array}$

Max. Test Area (L x W) 686 x 604mm (27 x 23.8")

Max. Component Height 55mm standard 110mm optional

Max Board Thickness 14mm

Automatic test program generation and debug

Test Type

ELECTRICAL TEST

In-Circuit Test

All-Nets Short Circuit Test

Nodal Impedance, Voltage and Insulation Test

Open Pin Scan Power-On Test

Discharge Capacitor Test Voltage Spike Detection Power Supply Test

Functional Test

Flashing via On-Board Programming

Boundary Scan Waveform Capture 5G RF Test

Insulation Resistance Test with HV Probe

OTHER TESTS

Light Chromaticity & Intensity test Flying LED sensor

3D Laser Test Component height

Board warpage
Component alignment
Component presence
Tombstone

...

Optical Test OCR, OCV, component

presence, component orientation, 2D code

reading

Thermal Test IR camera for temperature

monitoring

ADDITIONAL PROBE UTILITIES

Multi-Probe units
Dynamic support rods
Pushing fingers
Markers

* For larger boards, please contact SPEA.













